FEATURES

- Integrated with 650V Power MOSFET and HV Startup Circuit
- Optimize Audible Noise, Improve System Stability
- Multi-Mode Control with Audio Noise Free Operation
- Supports Buck and Buck-Boost Topologies
- Default 12V Output with FB floated
- Less than 50mW Standby Power
- Green Mode Operation for High Efficiency
- Good Line and Load Regulation
- Built-in Soft Start
- Build in Protections:
 - Over Load Protection (OLP)
 - Cycle-by-Cycle Current Limiting (OCP)
 - Output OVP
 - VDD OVP, UVLO & Clamp
- Available with SOP-8 and DIP-8 Package

APPLICATIONS

- Small Home Appliance
- Industry Controls

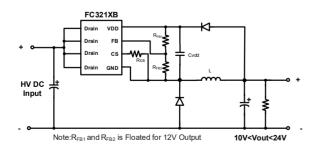
GENERAL DESCRIPTION

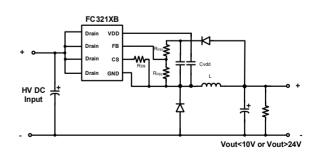
FC321XB family is a high performance Switch Mode Power Supply Switcher for low power off-line application with minimum components in typical buck solution. This family has built-in high break down voltage MOSFET to withstand high surge input.

Unlike conventional PWM control, there's no fixed internal clock in FC321XB family to trigger the GATE driver, the switching frequency is changed according to the load condition. The multi-mode PWM control is integrated to simplify circuit design and achieve good line and load regulation without audio noise generated. The peak current limit changes according to the real load condition for low standby power in no load.

FC321XB integrates functions and protections of Under Voltage Lockout (UVLO), Cycle-by-cycle Current Limiting (OCP), Output OVP, On-chip Thermal Shutdown, Over Load Protection (OLP), VDD OVP with Auto Recovery Mode Protection, etc.

TYPICAL APPLICATION CIRCUIT



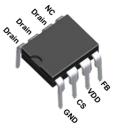




Pin Configuration



SOP-8



DIP-8

Marking Information













Typical Output Power Table (1)

Product	Package	R _{dson}	Vo	Load Current @85-265Vac, BUCK
FC321AB	SOP-8	15Ω	>2V	lo<250mA
F02240B	SOP-8	8Ω	>2V	200mA <lo<400ma< td=""></lo<400ma<>
FC3210B	DIP-8	8Ω	>2V	200mA <lo<400ma< td=""></lo<400ma<>
FC2244B	SOP-8	4Ω	>2V	350mA <lo<700ma< td=""></lo<700ma<>
FC3211B	DIP-8	4Ω	>2V	350mA <lo<700ma< td=""></lo<700ma<>
FC3212B	DIP-8	2Ω	>2V	650mA <lo<900ma< td=""></lo<900ma<>

⁽¹⁾ Default for Buck Converter Application. The practical output power is determined by the output voltage and thermal condition.

Pin Description

Pin Number (SOP-8)	Pin Number (DIP-8)	Pin Name	I/O ⁽²⁾	Description	
1	3	VDD	Р	The power supply and the output voltage feedback pin. For the normal operation, a capacitor with 1µF is recommended to connect to this pin	
2	1	GND	G	The ground reference for the IC	
3	4	FB	I	Feedback Input. Left open for default 12V output	
4	2	cs	I	Current Sensing Input	
5,6,7,8	6,7,8	Drain	Р	The Power MOSFET Drain	
/	5	NC	-	No Function Pin and Left Floating in Application	

⁽²⁾ I - Input, O - Output, P - Power, G - Ground.

Revision No: 0

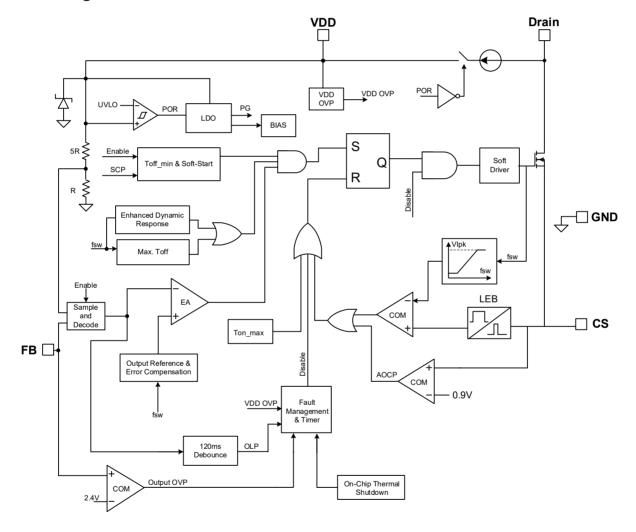


Ordering Information

Part Number (3)	Description		
FC321ABSGA, FC3210BSGA, FC3211BSGA	SOP-8, Halogen free in T&R, 4000 Pcs/Reel		
FC3210BSDP, FC3211BDP, FC3212BDP	DIP-8, Pb free, 50 Pcs/Tube		

⁽³⁾ Suffix "A" - Tape&Reel.

Block Diagram





Absolute Maximum Ratings (4)

Parameter	Value	Unit	
Drain - GND Voltage Range	-0.3 to 650	V	
VDD - GND Voltage Range		-0.3 to 30	V
VDD Pin Clamp Current		10	mA
FB, CS - GND Voltage Range		-0.3 to 7	V
Package Thermal Resistance – Junction to A	ambient (SOP-8)	165	°C/W
Package Thermal Resistance – Junction to A	ambient (DIP-8)	105	°C/W
Maximum Junction Temperature		150	°C
Storage Temperature Range		-65 to 150	°C
Lead Temperature (Soldering, 10sec.)	260	°C	
ESD Capability, HBM (Human Body Model)	3	kV	
FC321AB		0.8	А
Maximum Internal MOSFET DC Drain	FC3210B	1	А
Current	FC3211B	2	А
	FC3212B	4	А
	FC321AB		
Maximum Internal MOSFET Pulse Drain Current	FC3210B	4	А
(Continues 100µs)	FC3211B	8	А
	FC3212B	16	А

⁽⁴⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(5) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

Recommended Operation Conditions

Parameter	Value	Unit
Operating Junction Temperature	-40 to 125	°C
Operation Switching Frequency	40 to 60	kHz



Electrical Characteristics (Ta = 25℃, If Not Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit		
High Voltage Startup Section (HV Pin)								
I _{HV_st}	HV Charging Current	Drain=40V, VDD=6V		1.3		mA		
HV_leakage	HV Leakage Current	Drain=650V, VDD=12V			50	μΑ		
Supply Volt	age Section (VDD Pin)							
V _{DD_ON}	VDD Under Voltage Lockout Exit		6.4	7.5	8.6	V		
V _{DD_OFF}	VDD Under Voltage Lockout Enter			6.7		V		
V _{DD_Reg1}	VDD Regulation Voltage	FB is floating	12.4	12.6	12.8	V		
I _{VDD_st}	Start-up Current	No switching		180		μΑ		
I _{VDD_Op}	Operation Current	Fsw=60kHz		800		μΑ		
I _{VDD_Q}	Quiescent Current			200		μA		
V_{DD_OVP}	VDD OVP Threshold		26.4	28.5	30.6	V		
V _{DD_Clamp}	VDD Clamp Votage	IVDD=10mA		30		V		
Feedback S	ection (FB Pin)		1					
V_{FB_REF}	Internal Error Amplifier (EA) Reference Input		1.97	2.0	2.03	V		
V_{FB_OVP}	Output Over Voltage Protection (Output OVP) Threshold			2.4		V		
V_{FB_OLP}	Output Over Load Protection (Output OLP) Threshold			1.7		V		
T _{D_OLP}	Over Loading Debounce Time			120		ms		
Current Sen	se Input Section (CS Pin)	1	· I		1			
T _{LEB}	Leading Edge Blanking Time			350		ns		
T _{D_OCP}	Over Current Detection and Control Delay			100		ns		
VIPK	Normal Peak Current Limit		0.49	0.55	0.61	V		
VAOCP	Abnormal Over Current Protection Threshold			0.9		V		
Timer Section		,	1					
T _{OFF_min_norm}	Normal Minimum OFF time		14.5	16	17.5	μs		
Toff_max_nom	Nominal Maximum OFF Time			1.4		ms		
Toff_max_fdr	Maximum OFF Time in Fast Dynamic Response Mode			420		μs		

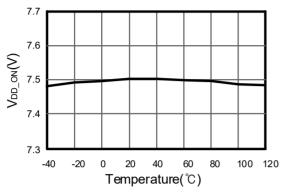


_	Maximum ON Time			40	
T _{ON_max}	Maximum ON Time			12	μs
T _{ss}	Internal Soft Start Time			3	ms
T _{Auto_Recovery}	Protection Auto Recovery Debounce Time			1.2	S
On-Chip The	ermal Shutdown				
TsD	Thermal Shutdown Trigger Point ⁽⁶⁾			150	°C
Power MOSI	FET Section (Drain Pin)				
V _{BR}	Power MOSFET Drain Source Breakdown Voltage		650		V
		FC321AB		15	Ω
Rdoon	Static Drain-Source On Resistance	FC3210B		8	Ω
		FC3211B		4	Ω
		FC3212B		2	Ω

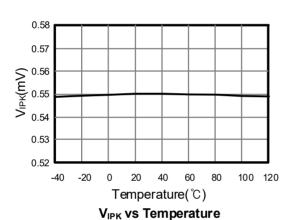
⁽⁶⁾ Guaranteed by design.



Characterization Plots



V_{DD ON} vs Temperature



Toff_min_nom(µs) 17 16 15 14

19

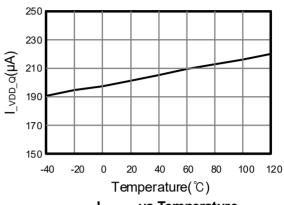
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-40 -20 0

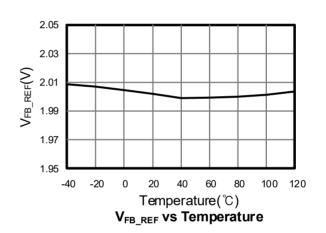
T_{off_min_norm} vs Temperature

Temperature(°C)

20 40 60 80 100 120



I VDD Q vs Temperature



FC321XB



High Performance Low Cost Off-line PWM Power Switch

Operation Description

FC321XB family integrates a high voltage power MOSFET switch and a multi-mode PWM controller. It is optimized for off-line non-isolated buck or buck-boost applications in small home appliances and linear regulator replacement. The IC utilizes the multi-mode PWM control to regulate output with high precision and lowest components count.

Very Low Operation Current

The standby operating current in FC321XB is as small as $200\mu A$ (typical). The small operating current results in higher efficiency and reduces the VCC hold-up capacitance requirement.

High Voltage Start-Up Operation with Less than 50mW Standby Power

In FC321XB, a 650V high voltage startup cell is integrated. During startup, the internal startup circuit is enabled and a HV current source charges the VDD hold up capacitor Cvdd through Drain pin, as shown in "Block Diagram". When VDD reaches UVLO turn-on voltage (7.5V typical), the IC begins switching and the IC current consumed increased to 0.8mA (typical). The VDD is charged by the output through the feedback diode in steady state, which result in less than 50Mw standby power with the combination of high voltage startup cell.

Current Limit and Leading Edge Blanking

There's a programmable current limit for current sensing voltage from CS Pin, which is changed according to the system switching frequency. When the sampled voltage exceeds the internal threshold, the power MOSFET is turned off for the remainder of that cycle. An internal leading edge blanking circuit is built in. During this blanking period (300ns, typical), the cycle-by-cycle current limiting comparator is disabled and cannot switch

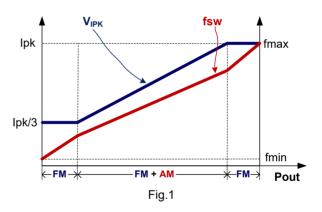
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off the GATE driver.

Multi-Mode PWM Control

To meet the tight requirement of averaged system efficiency and no load power consumption, a hybrid of frequency modulation (FM) and amplitude modulation (AM) is adopted in FC321XB which is shown in the Fig 1.

Around the full load, the system operates in FM mode. When normal to light load conditions, the IC operates in FM+AM mode to achieve excellent regulation and high efficiency. When the system is near zero loading, the IC operates in FM again for standby power reduction. In this way, the no-load consumption can be less than 50mW.



Constant Voltage Control

During the power MOSFET off period, FC321XB samples the FB pin signal which indicates the output voltage, then using the internal Sample & Hold circuit and constant voltage control circuit to guarantee FB pin voltage meet the internal reference V_{FB_REF} (typically 2.0V). So that constant output voltage is achieved.

Below equation approximately determines the output voltage:

$$Vo = 2.0V * \frac{Rup + Rdown}{Rdown}$$

8/12

FC321XB



High Performance Low Cost Off-line PWM Power Switch

Since the sampling of FB is affected by the isolation diode, it is necessary to adjust the FB voltage dividing resistance in practical application.

Soft Start

FC321XB features an internal 4ms (typical) soft start that slowly increases the switching frequency during startup sequence. Every restart attempt is followed by the soft start activation.

Output Over Voltage Protection (OVP)

In FC321XB, if the sampled FB voltage is larger than 2.4V and lasts for three continuous PWM cycles, the IC will enter into Output Over Voltage Protection (Output OVP) mode, in which auto recovery mode will be followed.

Over Load Protection (OLP) / Short Load Protection (SLP)

If over load or short load condition occurs, the output and the feedback voltage drop down to be lower than V_{FB_OLP} . If this fault is present for more than 120ms (typical), the protection will be triggered, the IC will experience an auto-restart mode (as mentioned below).

Abnormal Over Current Protection (AOCP)

When in heavy load or output short condition, the inductor current may be increased too large. To avoid system components damaged, there's a abnormal over current limit (typically 0.9V) for CS Pin. When the CS voltage is larger than this threshold, the internal power MOSFET is turned off immediately and is to be turned on again after 128µs.

On Chip Thermal Shutdown

FC321XB integrates thermal shutdown function. When the IC junction temperature is higher than 150 $^{\circ}$ C, IC shuts down and enters into auto-restart

mode (as mentioned below).

• Enhanced Dynamic Response

In FC321XB, the dynamic response performance is optimized to reduce output drop in load transient.

• Audio Noise Free Operation

In FC321XB, the optimized combination of frequency modulation and CS peak voltage modulation algorithm can provide audio noise free operation from full loading to zero loading.

VDD Over Voltage Protection (OVP) and Zener Clamp

When VDD voltage higher than V_{DD_OVP} (typically 28V), the IC will stop switching. This will cause VDD fall down to be lower than V_{DD_OFF} (typically 7V) and then the system will restart up again. An internal 30V (typical) zener clamp is integrated to prevent the IC from damage.

Protections with Auto-Restart

In the event of protections, the IC enters into autorestart and an internal timer begins counting, wherein the power MOSFET is disabled. When 1.2s had been counted, the IC will reset and start up the system again. However, if the fault still exists, the system will experience the above mentioned process.

Soft Totem-Pole Gate Driver

FC321XB has a soft totem-pole gate driver with optimized EMI performance.





Application Information

PCB Layout Guide

Good PCB layout is very important to FC321XB's operation, which helps to improve system reliability, EMI and thermal performance. Follow below guidelines to optimize performance.

(1) Power Loop Routing:

As shown in fig.2, minimize the power loop area of ① and ② as small as possible. Power loop ① is formed by input capacitor – IC – inductor – output capacitor. Power loop ② is formed by inductor – output capacitor – freewheeling diode. Make sure these two loop area reduce to its minimum.

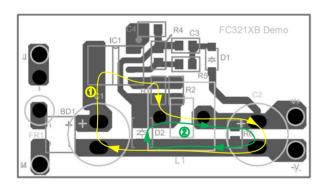


Fig.2

(2) Feedback Routing:

As shown in fig.3, the feedback loop ③ is formed by inductor — feedback diode — FB divided resistor//FB capacitor — IC. This loop is most important to system operation. Make sure these guidelines below been checked when layout: a)

Put the feedback loop out of the main power loop ① and ② , and minimize this loop area as small as possible; b) Do not route FB pin line too long, and do not route this line beneath the IC, or system may not operation normally; c) Put the components (FB divided resistor and FB capacitor) of this loop close to IC as much as possible, and far away from the power inductor; d) Place the output feedback point at the positive of the output capacitor, and do not route this line beneath the power inductor or freewheeling diode in case high-frequency noise coupled; e) Make sure signal ground of FB line and IC are connected first, then connect to power ground of inductor through a single point.

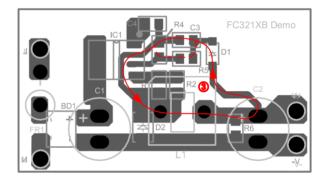


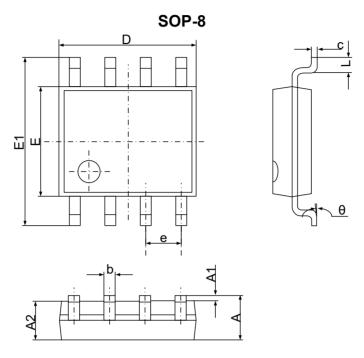
Fig.3

(3) Additional Notes:

a) When π filter circuit is added after the bridge, make sure power inductor far away from the π filter inductor; b) Connect the drain pin of FC321XB to a large cooper area to improve thermal performance if possible.



Package Dimension



Symbol	Dimensions i	n Millimeters	Dimensions in Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.300	1.500	0.051	0.059	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.007	0.010	
D	4.700	5.100	0.185	0.201	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



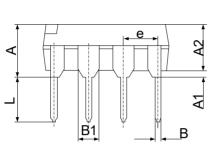


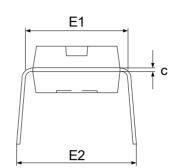
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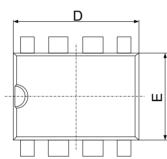
High Performance Low Cost Off-line PWM Power Switch

Package Dimension (Continued)

DIP-8







Symbol	Dimensions in Millimeters		Dimensions in Inches			
	Min.	Max.	Min.	Max.		
Α	3.600	4.150	0.142	0.163		
A1	0.510	-	0.020	-		
A2	3.150	3.400	0.124	0.134		
В	0.380	0.560	0.015	0.022		
B1	1.524	1.524 (BSC)		0.060 (BSC)		
С	0.200	0.350	0.008	0.014		
D	9.000	9.400	0.354	0.370		
E	6.200	6.500	0.244	0.256		
E1	7.620	7.620 (REF)		(REF)		
е	2.540 (BSC)		0.100	(BSC)		
L	3.000	3.600	0.118	0.142		
E2	7.620	9.300	0.300	0.366		